

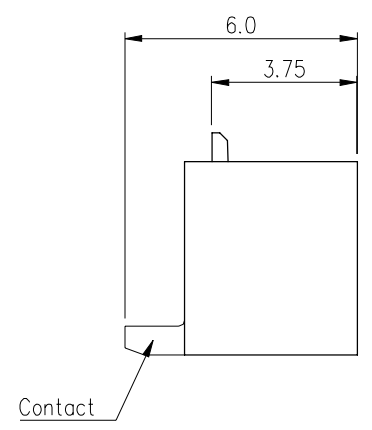
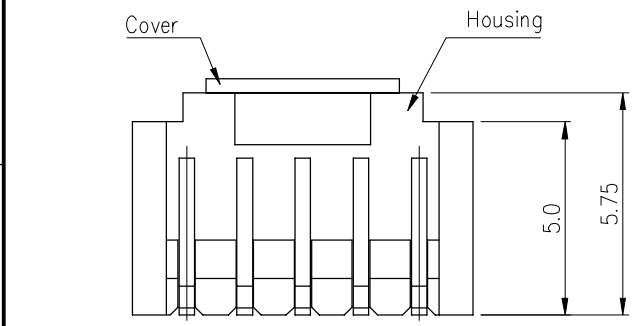
- NOTES:
- MATERIAL:
 - HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP., UL94V-0.
 - CONTACT: COPPER ALLOY
 - FINISH:
 - CONTACT: 50~100u" NICKEL UNDERPLATING OVERALL.
 - GOLD FLASH PLATING(1~3u") .
 - 100~200u" TIN PLATING ON SOLDER TAILS,
 - 100~200u" PURE TIN(MATT TIN)PLATING OVERALL.
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-50289-XXXX-XXX
 - PACKAGE PLS. REFER TO 88738-XXXX(-WT)-TRP
 - PART NUMBER

P/N LEGEND
50293-XXX X X-XXX

PACKING
0: TAPE & REEL
7: TAPE & REEL WITH COVER
8: TUBE WITH COVER

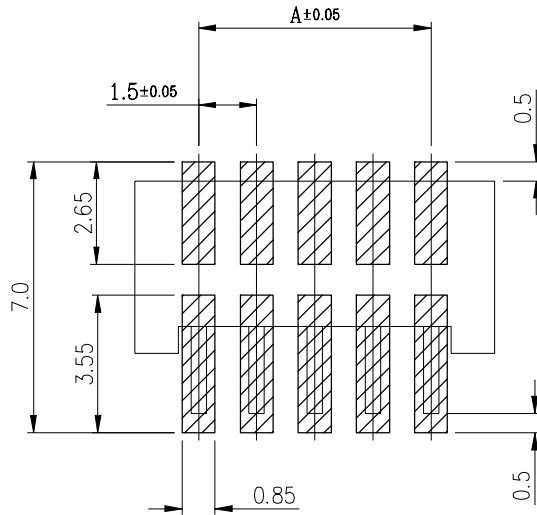
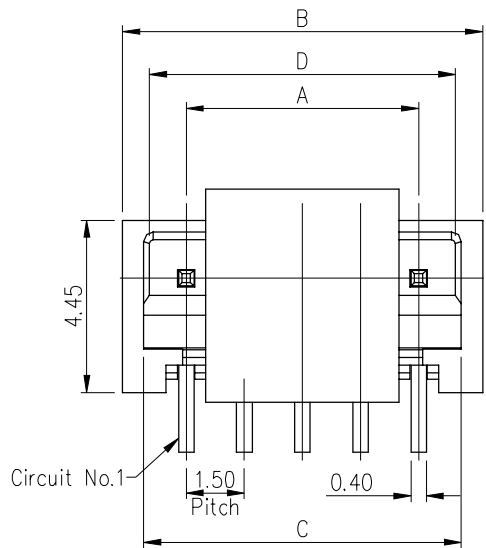
XXX	Material&Color	Cover	PACKAGE
001	LCP&Black	W/H Cover	88738-XXCR
002	LCP&White	W/H Cover	50293-XXXCR
003	LCP&Black	W/O Cover	50293-XXXCR
F01	LCP&Black	W/H Cover	88738-XXCR-05
W01	LCP&Black	W/H Cover	88738-XXCR-WT

PLATING
L: LEAD FREE (PURE TIN)
N: MATT TIN
1: GOLD FLASH PLATING

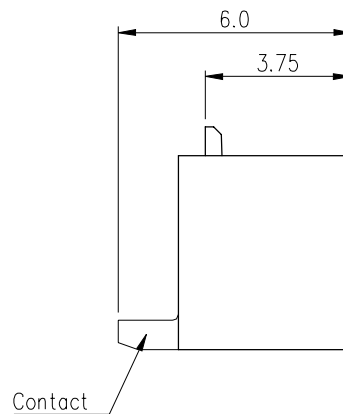
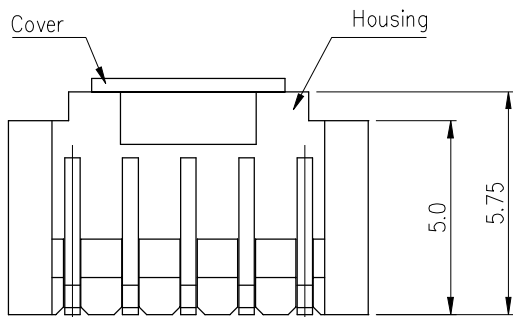


CKT	Dim A	Dim B	Dim C	Dim D
5	6.0	8.8	8.2	7.8

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 XX ±0.25 XXX ±0.15 XXXX ±0.1 ANGLES ±2°	DRAWN BY Rong, Li Ping CHECKED BY Lu, Jing Quan APPROVED BY Hsieh, Fu Yu	DATE 20/06/30 DATE 20/06/30 DATE 20/06/30		TITLE 1.5mm WTB Wafer Conn. SMT S/T Type
	UNITS mm SCALE - : -			



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



NOTES:

1. MATERIAL:
 - 1.1 HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP. UL94V-0 .
 - 1.2 CONTACT: COPPER ALLOY
2. FINISH:
 - 2.1 CONTACT: 50~100u" NICKEL UNDERPLATING OVERALL.
 - 1: GOLD FLASH PLATING(1~3u") .
 - L:100~200u" TIN PLATING ON SOLDER TAILS, N:100~200u" PURE TIN(MATT TIN)PLATING OVERALL.
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-50289-XXXXX-XXX
5. PACKAGE PLS. REFER TO 88738-XXXX(-WT)-TRP
6. PART NUMBER

P/N LEGEND

50293-XXX X X-XXX

CTKS

PACKING

- 0: TAPE & REEL
- 7: TAPE & REEL WITH COVER
- 8: TUBE WITH COVER

XXX	Material&Color	Cover	PACKAGE
001	LCP&Black	W/H Cover	50293-XXXXCR-02(15pin)
			50293-XXXXCR(Others)
002	LCP&White	W/H Cover	50293-XXXXCR
003	LCP&Black	W/O Cover	50293-XXXXCR
004	LCP&Black	W/O Cover	50293-XXXXCR-U
F01	LCP&Black	W/H Cover	50293-XXXXCR-05
W01	LCP&Black	W/H Cover	88738-XXCR-WT

PLATING

- L: LEAD FREE (PURE TIN)
- N: MATT TIN
- 1: GOLD FLASH PLATING

CKT	Dim A	Dim B	Dim C	Dim D
2	1.5	4.8	3.7	3.3
3	3.0	6.3	5.2	4.8
4	4.5	7.8	6.7	6.3
6	7.5	10.8	9.7	9.3
7	9.0	12.3	11.2	10.8
8	10.5	13.8	12.7	12.3
9	12.0	15.3	14.2	13.8
10	13.5	16.8	15.7	15.3
11	15.0	18.3	17.2	16.8
12	16.5	19.8	18.7	18.3
13	18.0	21.3	20.2	19.8
14	19.5	22.8	21.7	21.3
15	21.0	24.3	23.2	22.8
16	22.5	25.8	24.7	24.3
17	24.0	27.3	26.2	25.8
18	25.5	28.8	27.7	27.3
19	27.0	30.3	29.2	28.8
20	28.5	31.8	30.7	30.3

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Rong, Li Ping DATE 20/06/30		
	CHECKED BY Lu, Jing Quan DATE 20/06/30		TITLE 1.5mm WTB Wafer Conn. SMT S/T Type
	APPROVED BY Hsieh, Fu Yu DATE 20/06/30		
UNITS mm		SIZE A4	RFQ NO. N/A
SCALE - : -	SHEET NO. 2 OF 2	REV G	DWG NO. 50293-XXXXX-XXX